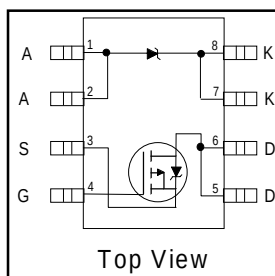


- Co-packaged HEXFET® Power MOSFET and Schottky Diode
- Ideal for Mobile Phone Applications
- Generation V Technology
- SO-8 Footprint

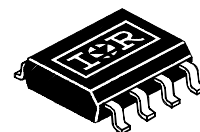


$V_{DSS} = -20V$
 $R_{DS(on)} = 0.18\Omega$
 Schottky $V_f = 0.39V$

Description

The FETKY™ family of co-packaged HEXFETs and Schottky diodes offer the designer an innovative board space saving solution for switching regulator applications. Generation 5 HEXFETs utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. Combining this technology with International Rectifier's low forward drop Schottky rectifiers results in an extremely efficient device suitable for use in a wide variety of portable electronics applications.

The SO-8 has been modified through a customized leadframe for enhanced thermal characteristics. The SO-8 package is designed for vapor phase, infrared or wave soldering techniques.



SO-8

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter		Maximum	Units
$I_D @ T_A = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS}@4.5V$ ④	-2.9	A
$I_D @ T_A = 70^\circ\text{C}$		-2.3	
I_{DM}		-23	
$P_D @ T_A = 25^\circ\text{C}$	Power Dissipation ④	2.0	W
$P_D @ T_A = 70^\circ\text{C}$		1.3	
	Linear Derating Factor	16	mW/°C
V_{GS}	Gate-to-Source Voltage	± 12	V
dv/dt	Peak Diode Recovery dv/dt ②	-5.0	V/ns
T_J, T_{STG}	Junction and Storage Temperature Range	-55 to +150	°C

Thermal Resistance Ratings

Parameter		Maximum	Units
$R_{\theta JA}$	Junction-to-Ambient ④	62.5	°C/W

Notes:

- ① Repetitive rating; pulse width limited by maximum junction temperature (see figure 11)
- ② $I_{SD} \leq -2.2A$, $di/dt \leq -50A/\mu s$, $V_{DD} \leq V_{(BR)DSS}$, $T_J \leq 150^\circ\text{C}$
- ③ Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$
- ④ Surface mounted on FR-4 board, $t \leq 10\text{sec}$.

MOSFET Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Parameter		Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	-20	—	—	V	$V_{GS} = 0V$, $I_D = -250\mu A$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	0.070	0.180	Ω	$V_{GS} = -4.5V$, $I_D = -2.9A$ ③
		—	0.115	0.375		$V_{GS} = -2.7V$, $I_D = -2.5A$ ③
$V_{GS(th)}$	Gate Threshold Voltage	-0.70	—	—	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$
g_{fs}	Forward Transconductance	4.0	—	—	S	$V_{DS} = -16V$, $I_D = -2.2A$
I_{DSS}	Drain-to-Source Leakage Current	—	—	-1.0	μA	$V_{DS} = -16V$, $V_{GS} = 0V$
		—	—	-25		$V_{DS} = -16V$, $V_{GS} = 0V$, $T_J = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	-100	nA	$V_{GS} = -12V$
	Gate-to-Source Reverse Leakage	—	—	100		$V_{GS} = 12V$
Q_g	Total Gate Charge	—	15	22	nC	$I_D = -2.2A$
Q_{gs}	Gate-to-Source Charge	—	2.2	3.3		$V_{DS} = -16V$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	6.0	9.0		$V_{GS} = -4.5V$ (see figure 10) ③
$t_{d(on)}$	Turn-On Delay Time	—	8.4	—	ns	$V_{DD} = -10V$
t_r	Rise Time	—	26	—		$I_D = -2.2A$
$t_{d(off)}$	Turn-Off Delay Time	—	51	—		$R_G = 6.0\Omega$
t_f	Fall Time	—	33	—		$R_D = 4.5\Omega$ ③
C_{iss}	Input Capacitance	—	610	—	pF	$V_{GS} = 0V$
C_{oss}	Output Capacitance	—	310	—		$V_{DS} = -15V$
C_{rss}	Reverse Transfer Capacitance	—	170	—		$f = 1.0\text{MHz}$ (see figure 9)

MOSFET Source-Drain Ratings and Characteristics

Parameter		Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	-2.0	A	
I_{SM}	Pulsed Source Current (Body Diode)	—	—	-23		
V_{SD}	Body Diode Forward Voltage	—	—	-1.2	V	$T_J = 25^\circ\text{C}$, $I_S = -2.0A$, $V_{GS} = 0V$
t_{rr}	Reverse Recovery Time (Body Diode)	—	43	65	ns	$T_J = 25^\circ\text{C}$, $I_F = -2.3A$
Q_{rr}	Reverse Recovery Charge	—	44	66	nC	$di/dt = 100A/\mu s$ ③

Schottky Diode Maximum Ratings

	Parameter	Max.	Units	Conditions
$I_{F(av)}$	Max. Average Forward Current	1.7	A	50% Duty Cycle. Rectangular Wave, $T_A = 25^\circ\text{C}$
		1.2		$T_A = 70^\circ\text{C}$
I_{SM}	Max. peak one cycle Non-repetitive Surge current	120	A	5 μs sine or 3 μs Rect. pulse
		11		10ms sine or 6ms Rect. pulse
				Following any rated load condition & with V_{RRM} applied

Schottky Diode Electrical Specifications

	Parameter	Max.	Units	Conditions
V_{FM}	Max. Forward voltage drop	0.50	V	$I_F = 1.0A$, $T_J = 25^\circ\text{C}$
		0.62		$I_F = 2.0A$, $T_J = 25^\circ\text{C}$
		0.39		$I_F = 1.0A$, $T_J = 125^\circ\text{C}$
		0.57		$I_F = 2.0A$, $T_J = 125^\circ\text{C}$
I_{RM}	Max. Reverse Leakage current	0.05	mA	$V_R = 20V$, $T_J = 25^\circ\text{C}$
		10		$T_J = 125^\circ\text{C}$
C_t	Max. Junction Capacitance	92	pF	$V_R = 5Vdc$ (100kHz to 1 MHz) 25°C
dv/dt	Max. Voltage Rate of Charge	3600	V/ μs	Rated V_R

Power Mosfet Characteristics

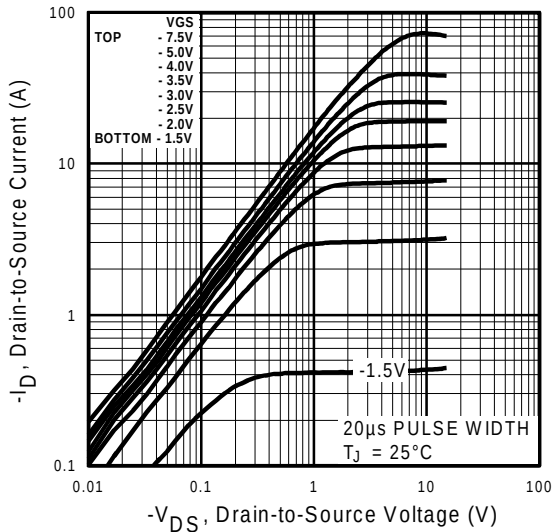


Fig 1. Typical Output Characteristics

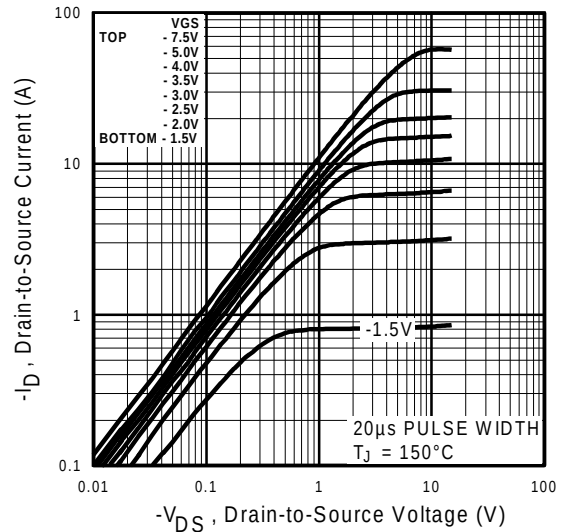


Fig 2. Typical Output Characteristics

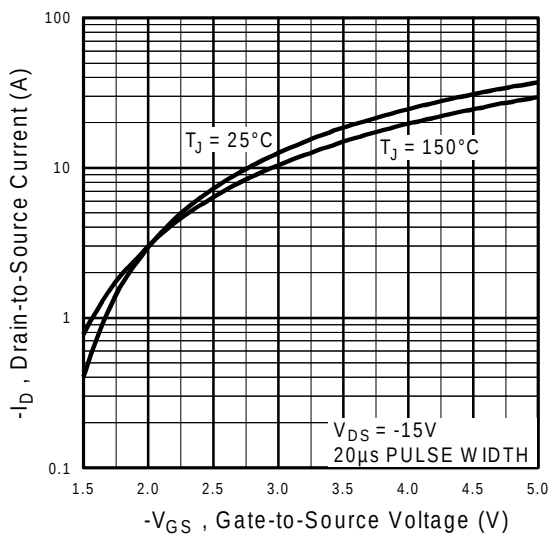


Fig 3. Typical Transfer Characteristics

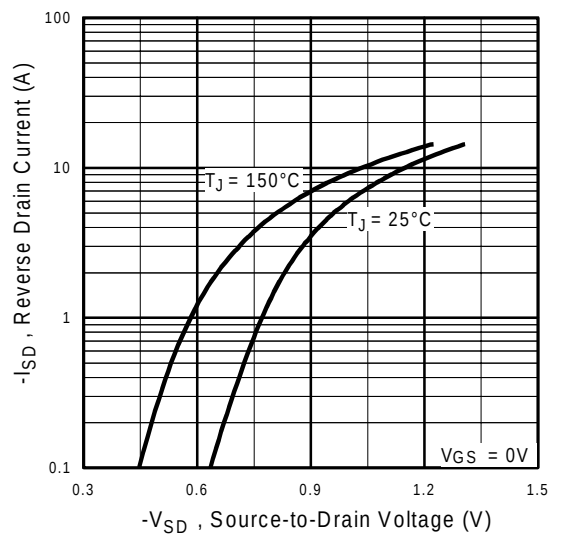


Fig 4. Typical Source-Drain Diode Forward Voltage

Power Mosfet Characteristics

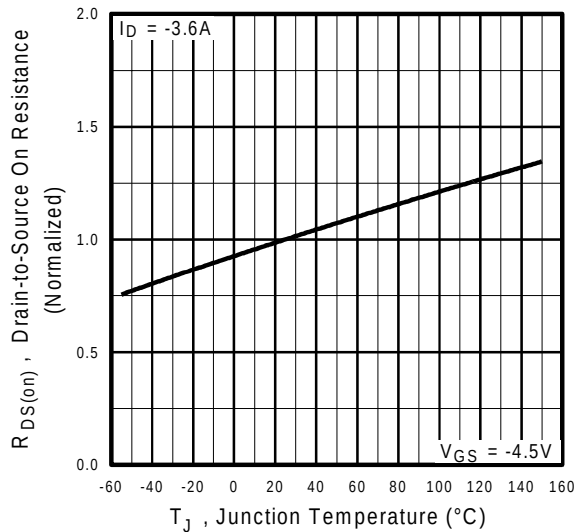


Fig 5. Normalized On-Resistance Vs. Temperature

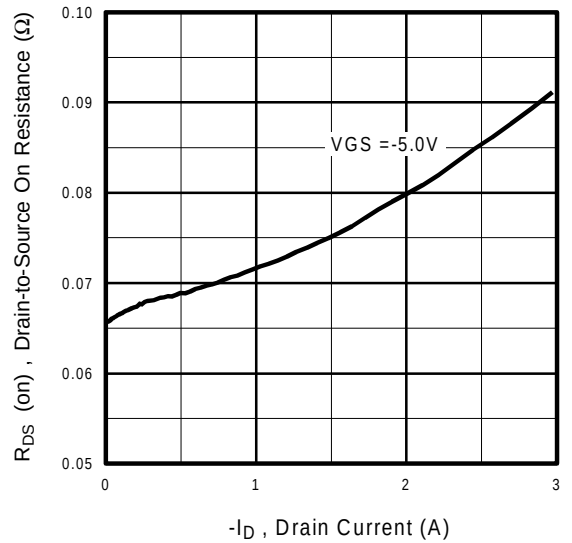


Fig 6. Typical On-Resistance Vs. Drain Current

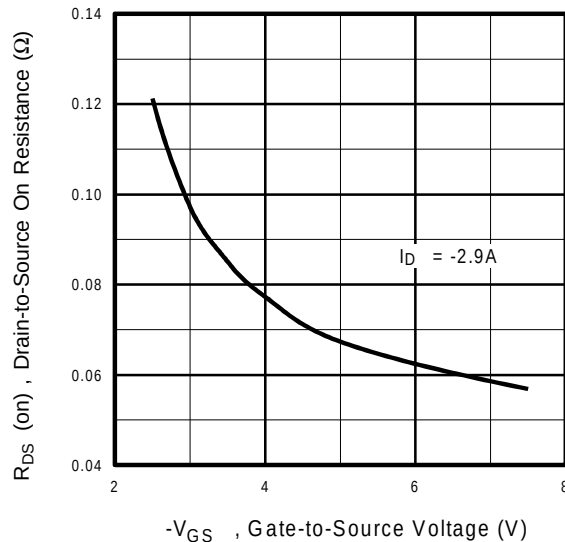


Fig 7. Typical On-Resistance Vs. Gate Voltage

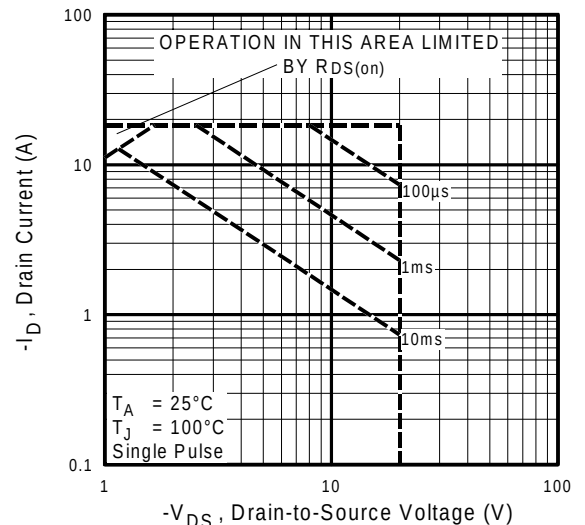


Fig 8. Maximum Safe Operating Area

Power Mosfet Characteristics

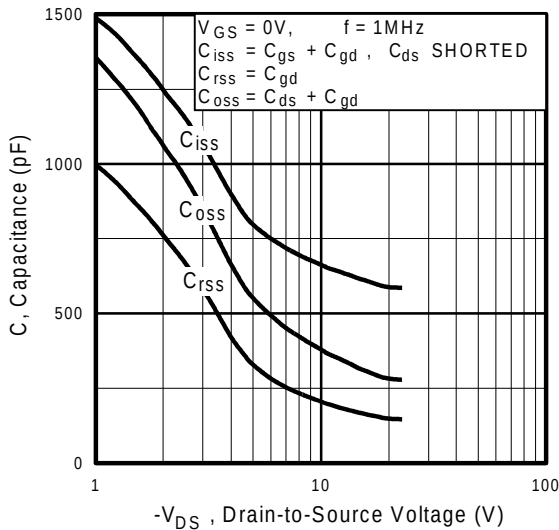


Fig 9. Typical Capacitance Vs. Drain-to-Source Voltage

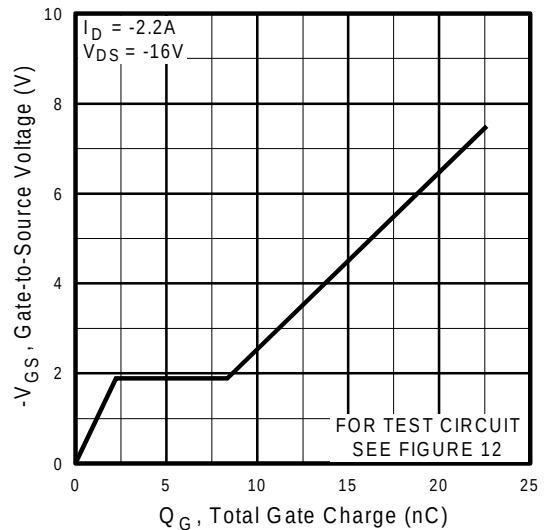


Fig 10. Typical Gate Charge Vs. Gate-to-Source Voltage

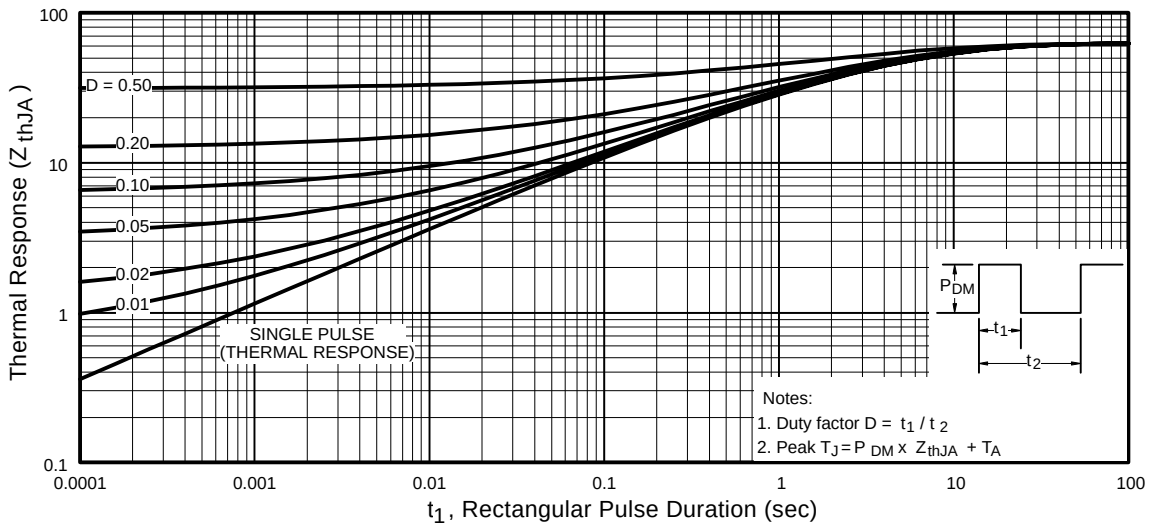


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

Schottky Diode Characteristics

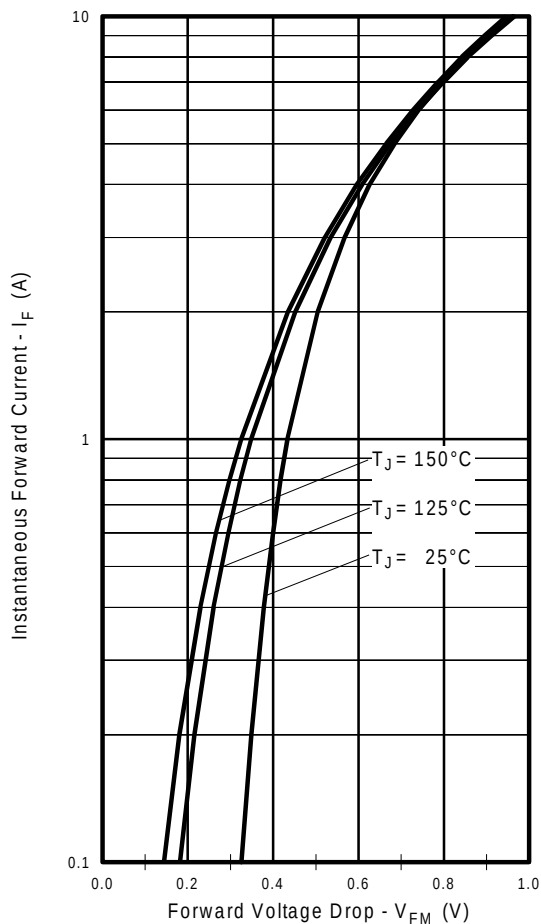


Fig. 12 -Typical Forward Voltage Drop Characteristics

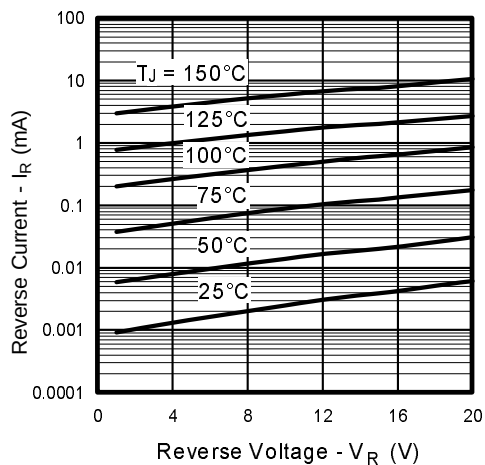


Fig. 13 - Typical Values of Reverse Current Vs. Reverse Voltage

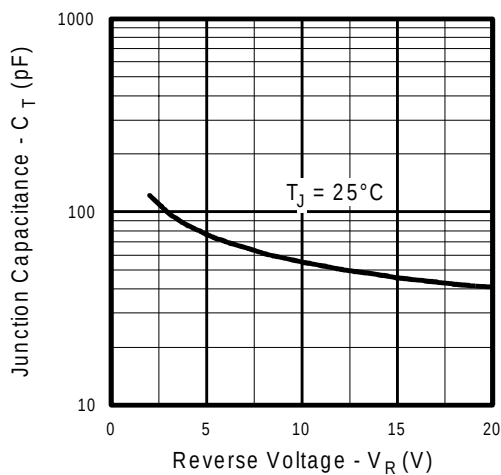
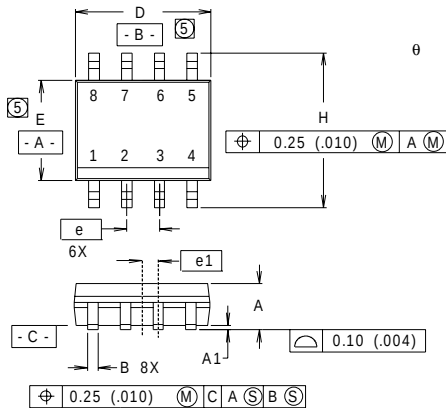


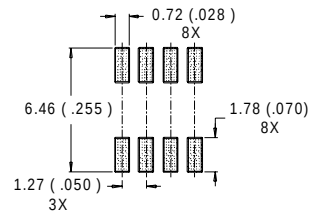
Fig.14 - Typical Junction Capacitance Vs. Reverse Voltage

SO-8 Package Details



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
B	.014	.018	0.36	0.46
C	.0075	.0098	0.19	0.25
D	.189	.196	4.80	4.98
E	.150	.157	3.81	3.99
e	.050 BASIC		1.27 BASIC	
e1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.011	.019	0.28	0.48
L	0.16	.050	0.41	1.27
θ	0°	8°	0°	8°

RECOMMENDED FOOTPRINT

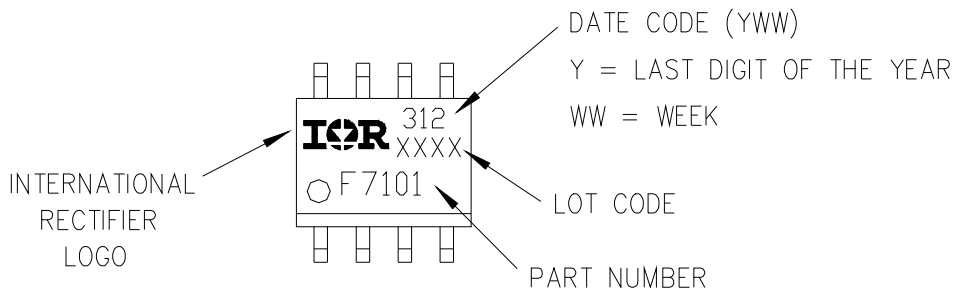


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
2. CONTROLLING DIMENSION : INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS
MOLD PROTRUSIONS NOT TO EXCEED 0.25 (.006).
6. DIMENSIONS IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE..

Part Marking (IRF7101 example)

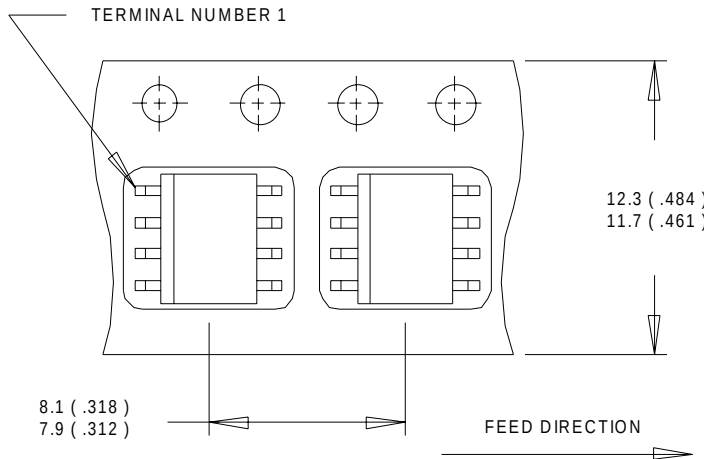
EXAMPLE: THIS IS AN IRF7101



IRF7324D1

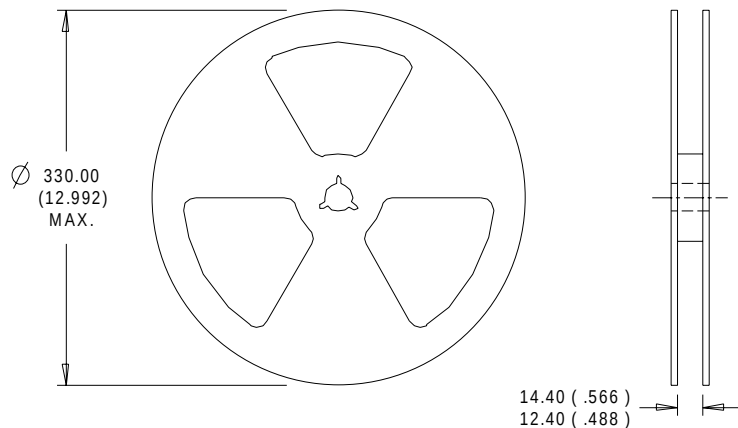
International
IOR Rectifier

Tape and Reel



NOTES:

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :

1. CONTROLLING DIMENSION : MILLIMETER.
2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

International
IOR Rectifier

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IR GERMANY: Saalburgstrasse 157, 61350 Bad Homburg Tel: ++ 49 6172 96590

IR ITALY: Via Liguria 49, 10071 Borgaro, Torino Tel: ++ 39 11 451 0111

IR FAR EAST: K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo Japan 171 Tel: 81 3 3983 0086

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IR TAIWAN: 16 Fl. Suite D. 207, Sec. 2, Tun Haw South Road, Taipei, 10673, Taiwan Tel: 886-2-2377-9936

<http://www.irf.com/>

Data and specifications subject to change without notice.

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